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KANETANI YASUHIKO**(54) **PRINTED BOARD AND MANUFACTURE
THEREOF**

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(57) Abstract:

PURPOSE: To improve mounting density of printed boards by opening blind holes from one surface of a printed board to one copper foil layer, laminating the boards with the hold disposed inside through an insulating layer, and forming a reflow pad at the outermost layer copper foil layer.

CONSTITUTION: A window 23 is irradiated with a laser 24 to remove an insulating layer 20 of an insulator 20, thereby opening a blind hold 25 reaching an outer conductive layer 22. The outer conductive layer 21 side is removed by etching to form a pattern 27. A first board and a second board are so superposed through an insulator 40 therebetween as to dispose the openings of blind holes 28, 38 inside the laminated layer, and hot pressed to manufacture a multilayer board 50. An outer layer formed of the layer 22, a plated layer 60, an outer conductive layer 32, and the layer 60 are etched to form reflow pads 70, 75 and conductive through holes 80, 85.

